

***Amendments to the Claims***

The listing of claims will replace all prior versions, and listings of claims in the application.

1 - 11. *(cancelled)*

12. *(original)*: A lithography system configured to reduce wafer slipping, comprising:

- (a) a wafer chuck configured to receive a wafer; and
- (b) an expander coupled to the wafer chuck to expand the wafer chuck and create an initial stress at an interface between the wafer and the wafer chuck.

13. *(currently amended)*: The system of claim 12, wherein said expander comprises:

an annular ~~ring~~tube coupled to said wafer chuck.

14. *(currently amended)*: The system of claim 13, wherein said annular ~~ring~~tube is coupled to an outer edge of said wafer chuck.

15. *(withdrawn)*: The system of claim 13, wherein said annular ring fits within a cavity in said wafer chuck.

16. *(withdrawn)*: The system of claim 12, wherein said expander comprises:  
a plurality of force actuators attached to said wafer chuck,

wherein said plurality of force actuators is configured to stretch said wafer chuck.

17. *(withdrawn)*: The system of claim 16, wherein said plurality of force actuators is dispersed evenly around said wafer chuck.

18. *(withdrawn)*: The system of claim 12, wherein said expander comprises:  
a heater configured to heat said wafer chuck.

19. *(withdrawn)*: The system of claim 18, wherein said heater is a contact heater disposed in contact with said wafer chuck.

20. *(withdrawn)*: The system of claim 18, wherein said heater is a proximity heater spaced apart from said wafer chuck.

21. *(withdrawn)*: The system of claim 18, wherein said heater comprises an electrical current source coupled to said wafer chuck to pass an electric current through said wafer chuck.

22. *(withdrawn)*: The system of claim 18, wherein said heater heats said wafer chuck with electromagnetic radiation.

23. *(original)*: The system of claim 12, wherein said expander is configured to expand said wafer chuck in a uniform manner.